



NOTES:

1. MATERIAL:
 - 1.1 HOUSING: THERMOPLASTIC, HIGH TEMP., UL94V-0;
 - 1.2 CONTACT: COPPER ALLOY
2. FINISH:
 - 2.1 CONTACT:
 - N: 50~100u" PURE TIN PLATING OVERALL
 - 50u" MIN. NICKEL UNDERPLATING OVERALL
3. REFLOW SOLDER CAPABLE TO 260°C PER ACES SPEC.
4. SPEC. PLS. REFER TO PS-51281-xxxxx-xxx
5. PART NUMBER

51318-XXX X X-XXX

NO OF CKT	XXX	HOUSING MATERIAL	HALOGEN FREE
PACKING	001	PA66 PLASTIC	HF
3: BAG		PLATING L: PURE TIN PLATING	

CKT	Dim A	Dim B
2	7.86	3.96
5	19.74	15.84

一般公差 TOLERANCES X ±0.5 XX ±0.15 X ±0.25 .XXX ±0.1 ANGLES ±2°		宏致電子股份有限公司 Aces Electronics Co.,Ltd.	
檢驗尺寸標示 SYMBOLS INDICATE CLASSIFICATION DIMENSION MARK IS CRITICAL DIM. MARK IS MAJOR DIM.	品名 (TITLE) 3.96mm WTB Wafer Conn T/H S/R R/A Type	製圖 (DR) TANGENHUI 15'/11/16 審核 (CHKD) ANDREW	核准 (APPD) CHARLESLEE
圖號 (DWG NO.) 51318-XXXXX-XXX	比例 (SCALE) 3:1	單位 (UNITS) mm	張數 (SHEET) 1 OF 1 尺寸 (SIZE) A4 版次 (REV) 0